

### Team SPIRIT 43 years of service

Continually Achieving and Improving Quality and Customer Satisfaction Through Our Spirit and Commitment to Excellence. ISO9001 and AS9100 Certifications



### SPIRIT ELECTRONICS



S D B A D V A N T A G E S

SDB SPEND CATEGORIES Veteran Owned

Woman Owned

Hub Zone Certified

Small Business



## TEAM SPIRIT'S STRENGTHS

### INFRASTRUCTURE

- Niche combination of inhouse offerings: Distribution, value-add services, test/screening, radiation services, circuit card assy.
- Sophisticated ERP system for inventory and operations management
- Program management & team support
- Secure supply chain with redundant counterfeit mitigation

### QUALITY

- Quality Management
   System integrated for high reliability quality operation
- Strive for 100% lot acceptance by customers
- Cybersecurity focus and CMMC, level 3 selfcertification
- Thorough vetting of external value-add sub-con suppliers
- QBRs with critical external providers, franchised OEM partners

### ENGINEERING

- ASIC design team with 3 decades of experience
- Legacy as back-end test provider for all Xilinx product, 20+ years
- On-site engineering support team for services (value-add, test and CCA)
- Large library to leverage cost savings and schedule reduction
- EOL & obsolescence support programs available



# Your One-Stop Shop

We are redefining the meaning of distribution in our industry with value add, test and assembly services now available under one roof.



### WE ARE THE BOM.

With inventory options for EOL and LTB, we're protecting your interest. We are a designated high reliability distributor and an accredited distributor for your EOL products. We are a franchised and authorized distributor for these brands:





















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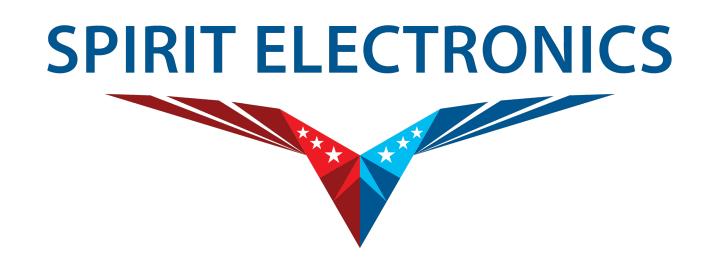


Sensing Solutions



 $EPC \cdot SPACE$ 





### BIG IDEAS FOR EVERY SPACE

### Products

Die & Wafer

Packaged product with value-add

 Efficient, thermally optimized and reliable SMD, MIL-STD-883 (/883) and Class-V/Q products for the defense, high-reliability (Hi-Rel), and radiation hardened / space marketplaces.





#### **Combination PCB**



Copper foil thickness: 8.6oz & 2oz copper on the very same layer

Number of Layers: 2- 6 Layers

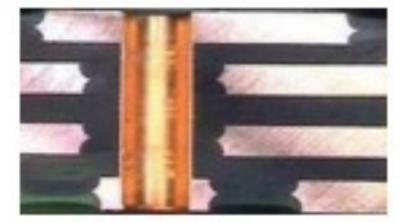
Board thickness: 0.051"-0.137" (1.3 - 3.5 mm)

Available: IVH / 11.4oz, 14.3oz and < 6.8oz copper for Inner layer

UL Certified



### **Heavy Copper PCB**



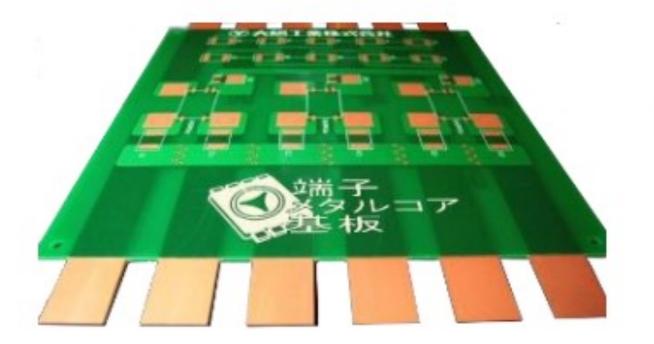
Copper foil thickness: 8.6/11.4/14.3oz (using rolled copper foil)

Number of Layers: 2-6 Layers (depending on Cu foil thickness)

Board thickness: 0.051"-0.137" (1.3-3.5 mm)

Available: IVH / less that 6.8oz for Inner layer

UL Certified

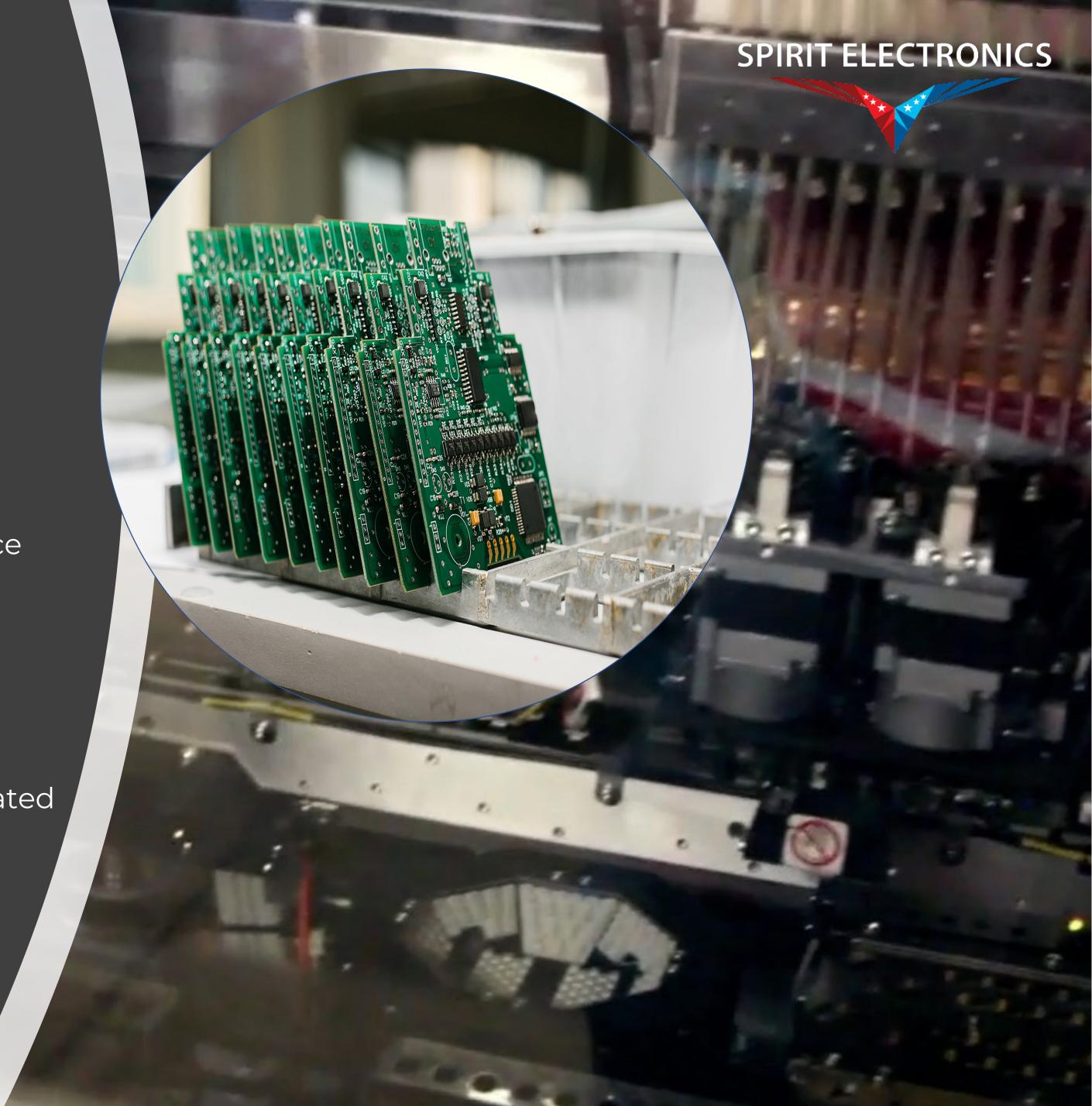


### Embedded Bus Bar PCB

Instead of using etching process to make traces, 14.3oz. or heavier Bus-Bar is made with rolled copper foils by metal fabrication, and it can be embedded in the PCB.

## Circuit Card Assembly Line

- 45,000 chip-per-hour pick & place machine
- High accuracy, can place an 03015 ultra-tiny chips, up to the industry's largest FPGAs.
- SMT/SMD thru-hole and mixed technology PCB assemblies
- Ability to trace a part all the way down to the reference designator on the board
- PCB sizes from 50mm x 50mm (2" x 2") to 810mm L
   x 480mm W
- 5300 sq ft dedicated to board assembly (Phx, AZ HQ Facility)
- Equipment: Screen Printer, Pick & Place, AOI (Automated Optical Inspection), Reflow Oven (10x 12.5" Zones)
- Prototype quantities, up to production volume runs
- Able and willing to handle high \$ ASP components



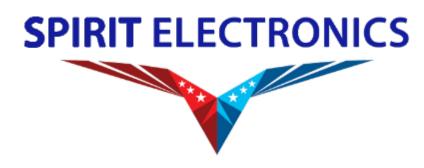
### IN-HOUSE VALUE-ADD SERVICES

- Temp Cycle
- Burn-In
- C-SAM
- HAST
- PIND
- Nitrogen Storage
- XRF
- Kitting

- SolderabilitySteam Age
- Laser Marking
- Solder-ExchangeHot Solder Dip
- Robotic BGARe-Ball
- Tape & Reel

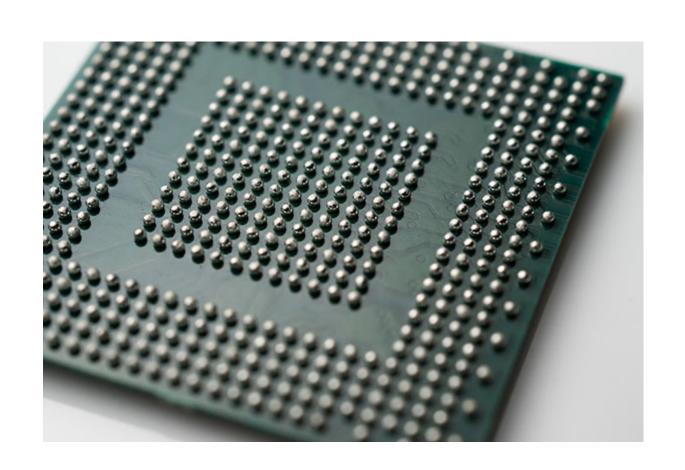


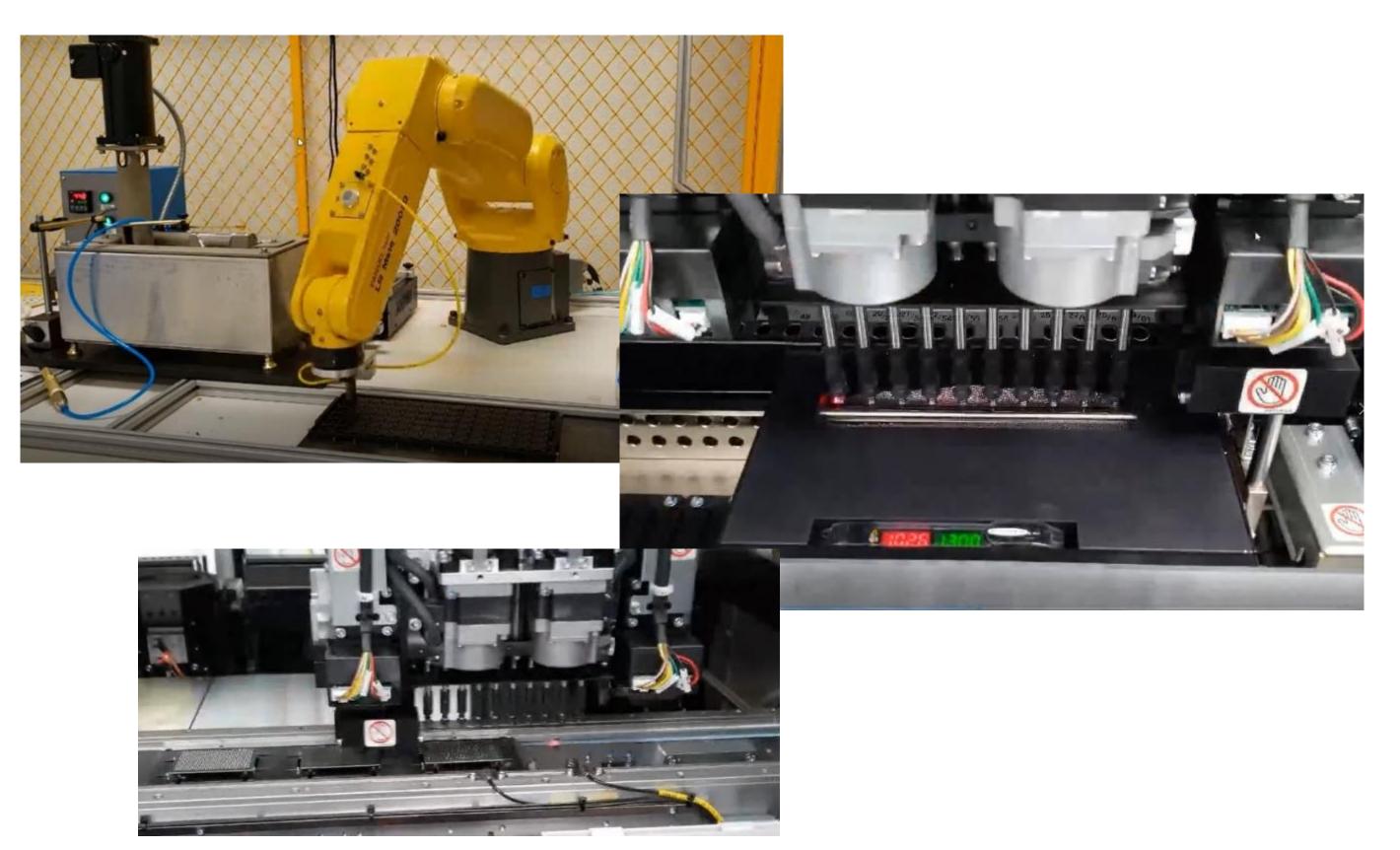




### Robotic BGA Reball

- High Precision
- Streamlined Process
- Robotic Ball Removal
- SMT Automated Flow
- MIL/Aero Focused



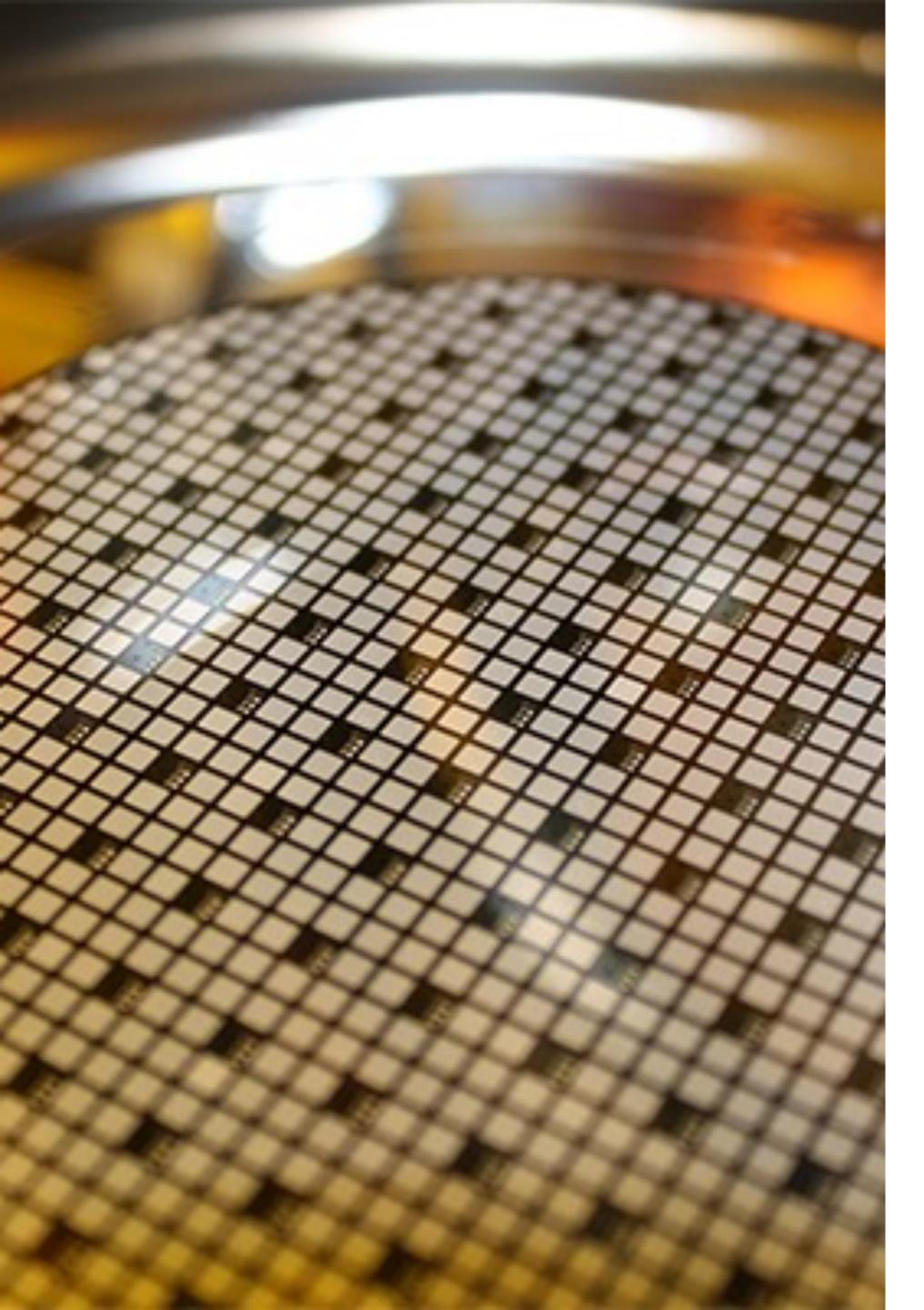




# HI-RELIABILITY VALUE-ADD SERVICES

MIL-STD-883 PEM QUAL

- Up-Screening
  - Extended temperature testing
  - Space-level screening
- Qualification & Reliability
  - •X-Ray
  - Temp cycling
  - Burn-in
  - C-SAM
  - Electrical testing
  - Preconditioning
  - HAST
  - DPA
- Radiation Effects Testing





### Wafer & Die Services

#### Performance:

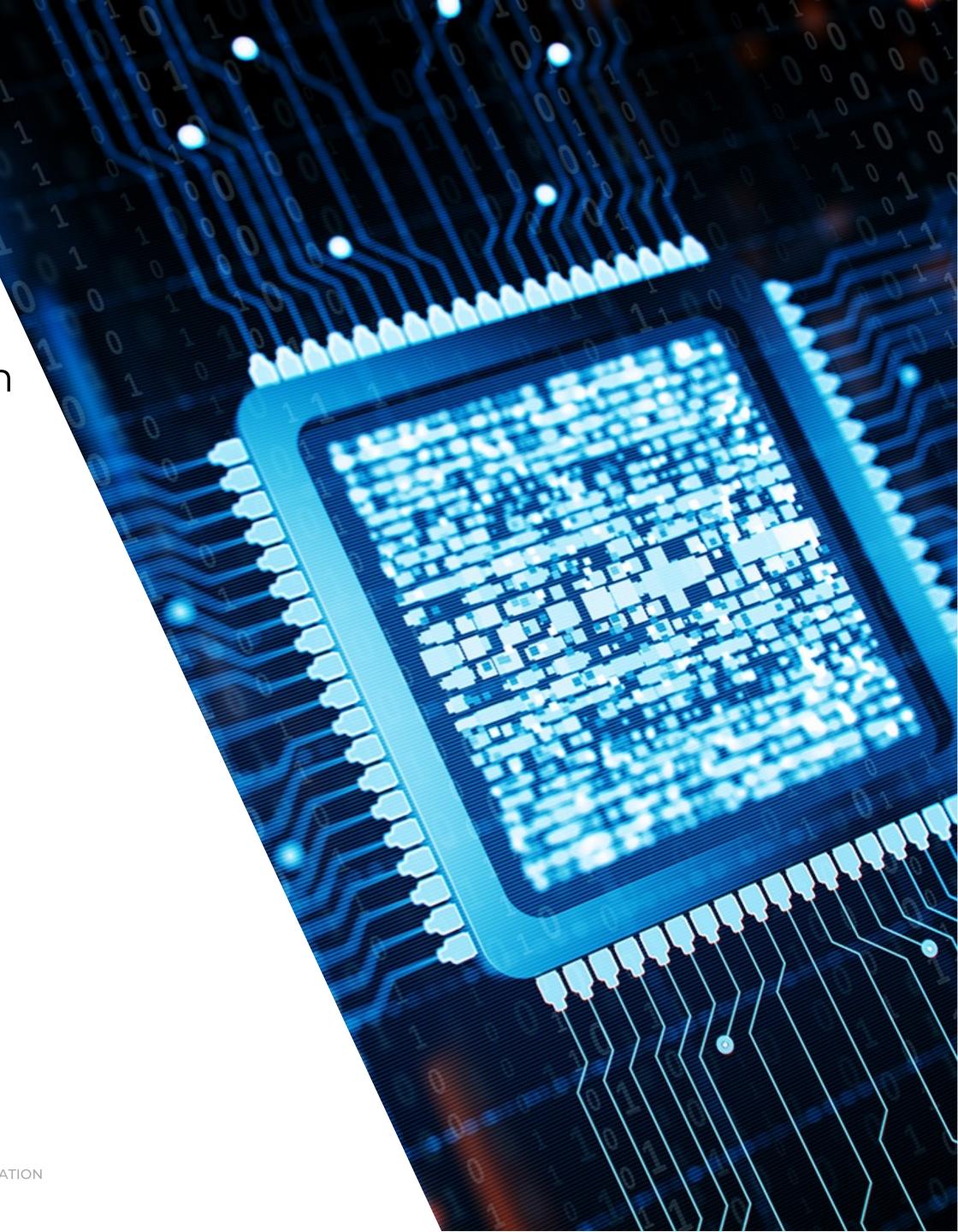
- Wafer Probing (hot & cold temperature)
- Wafer-Level Programming
- Wafer Thinning (to 50 microns)
- Wafer Sawing (to 300mm wafers)
- Wafer Mapping/Inking
- Wafer Dicing
- Pick-and-Place
- Visual Inspection (MIL-STD-883 or custom)
- Lot Qualification (Class H or K)
- Long-Term Die & Wafer Storage

### ASICs & SoCs

- ASIC test methodology and test pattern generation
- Memory built-in self-test (BIST)
- Scan insertion
- FPGA design and verification
- Design synthesis
- Custom integrated circuit solutions that solve problems and add value
- Robust ASIC design solutions for reliable operation in harsh environments

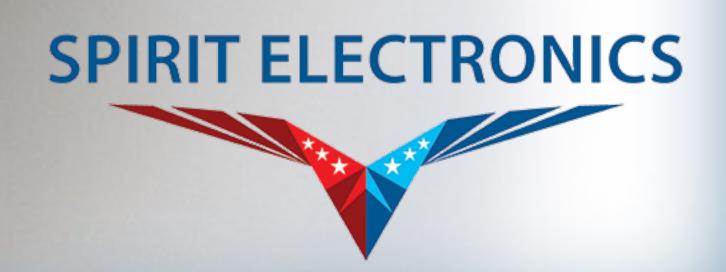
### RF Design

- From schematic to layout
- Enabling the IoT
- Meeting the challenges of 5G in RF PCB design





Accelerate your time-to-market with pre-screened and pre-qual'd components, now available as MOTS (Military-Off-The-Shelf) from Spirit Electronics. They are rigorously tested for reliability in a wide range of applications and optimized for performance, power and security.



### Data Sheets for Custom Devices

Eliminate the need for customer control devices.

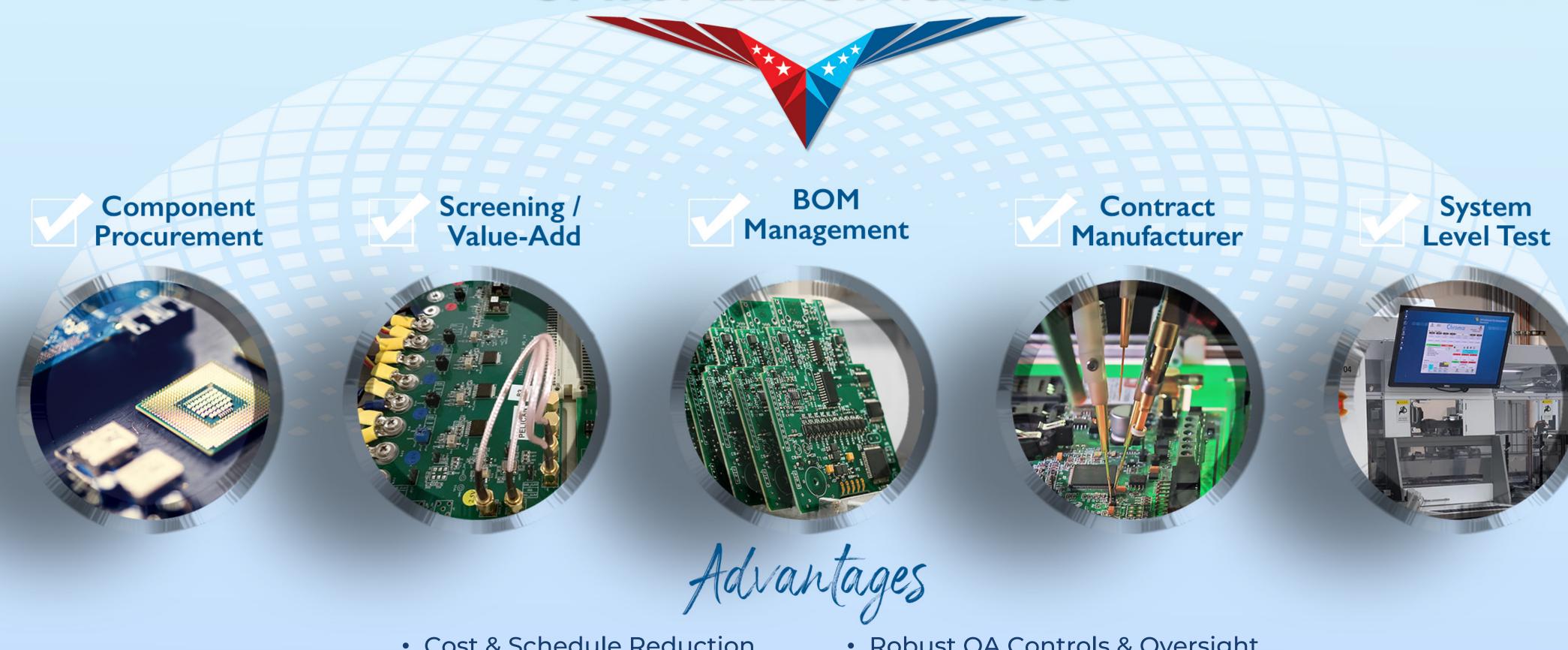
With more than 40 years of experience, Spirit Electronics has a wide breadth of engineering knowledge.

We are equipped to collaborate with your engineering team or create a customized engineering solution for your project.



### Fullurnkey solution

### SPIRIT ELECTRONICS



- Cost & Schedule Reduction
- Reduced Material Handling
- Care Custody and Control
- Robust QA Controls & Oversight
- Reduced Paperwork & Processing
- Expertise and Tribal Knowledge

One PO, One Supplier

# THANK YOU SPIRIT ELECTRONICS SPIRIT ELECTRONICS PROPRIETARY INFORMATION